

# APX-VNG0031PSD

**2mm Diameter Extended Visible InGaAs Position Sensitive Detector (PSD)** 

The APX-VNG0031PSD series are tetra-lateral 2mm diameter active area EXTENDED VISIBLE InGaAs position sensitive detectors. These high-accuracy position detection devices feature an enhanced sensitivity spectrum from 400nm to 1700nm, surpassing the standard InGaAs spectral response of 700nm to 1700nm. The devices are available in two inter-electrode resistance options of  $0.5 k\Omega$  and  $2.2 k\Omega$ . They are also available in a hermetically sealed TO-5 metal can or a Leadless Chip carrier (LCC) package.

# **Applications**

# Alignment Position Sensing Industrial Sensing Guidance Systems Targeting Communication

# **Features**

High Position Detection Accuracy

0.5kΩ or 2.2kΩ Inter-Electrode
Resistance

400-1700 nm Sensitivity

High Shunt Resistance

TO-5 or Leadlless Chip Carrier (LCC)

2mm Diameter Active Area





# Absolute Maximum Ratings at T<sub>A</sub>=23 °C

Parameter	Symbol	APX-VNG0031PSD-001		APX-VNG00	031PSD-002	APX-VNG00	031PSD-003	APX-VNG0	l lmi4	
		Min	Max	Min	Max	Min	Max	Min	Max	Unit
Reverse Voltage	$V_{R}$	-	7	-	7	-	7	-	7	V
Operating Temperature	T <sub>OP</sub>	-40	+125	-40	+125	-40	+125	-40	+125	°C
Storage Temperature	$T_{STG}$	-55	+125	-55	+125	-55	+125	-55	+125	°C
Package		TO-5		TO-5		Ceramic LCC		Ceramic LCC		

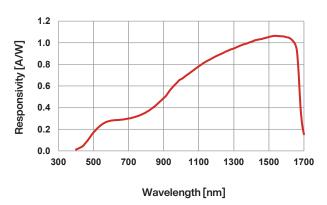
# Typical Electro-Optical Specifications at $T_A$ =23 °C

Parameter	Test Conditions		APX-VNG0031PSD-001		APX-VNG0031PSD-002			APX-VNG0031PSD-003			APX-VNG0031PSD-004			Unit	
			Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Onit
Active Area	-	A.A.	-	3.1	-	-	3.1	-	-	3.1	-	-	3.1	-	mm²
Active Area Diameter	-	A.A. <sub>Ø</sub>	-	2	-	-	2	-	-	2	-	-	2	-	mm
Spectral range	Spot Scan	Δλ	400	-	1700	400	-	1700	400	-	1700	400	-	1700	nm
Reponsivity	λ=632nm	$R_{\lambda}$	0.26	0.29	-	0.26	0.29	-	0.26	0.29	-	0.26	0.29	-	A/W
	λ=1060nm	$R_{\lambda}$	0.69	0.73	-	0.69	0.73	-	0.69	0.73	-	0.69	0.73	-	A/W
	λ=1550nm	$R_{\lambda}$	0.90	1.06	-	0.90	1.06	-	0.90	1.06	-	0.90	1.06	-	A/W
Capacitance	V <sub>R</sub> =0V; f=1MHz	$C_J$	-	250	400	-	250	400	-	250	400	-	250	400	pF
	V <sub>R</sub> =5V; f=1MHz	$C_J$	-	130	200	-	130	200	-	130	200	-	130	200	pF
Dark Current	V <sub>R</sub> =1V	I <sub>D</sub>	-	1	20	-	1	20	-	1	20	-	1	20	nA
	V <sub>R</sub> =5V	I <sub>D</sub>	-	50	150	-	50	150	-	50	150	-	50	150	nA
Shunt Resistance	V <sub>R</sub> =10mV	$R_{\scriptscriptstyleSH}$	2	20	-	5	20	-	2	20	-	5	20	-	МΩ
Inter- Electrode Resistance	Between diagonally opposing contacts	-	-	2.2	-	-	0.5	-	-	2.2	-	-	0.5	-	kΩ
Position Detection Error	V <sub>R</sub> =1V	PDE	-	20	-	-	20	-	-	20	-	-	20	-	μm

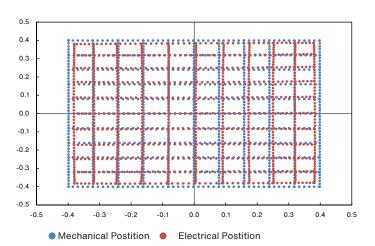




# **Typical Spectral Response**

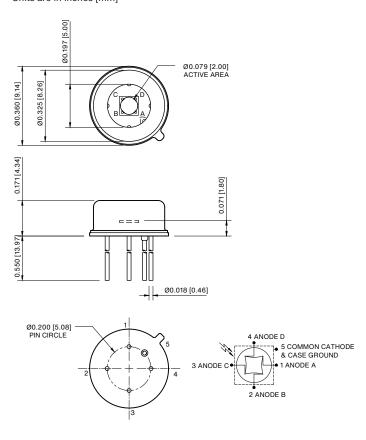


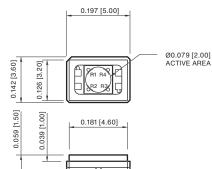
# **Position Error Scan**

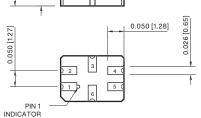


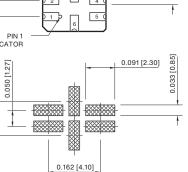
# **Mechanical Specification**

Units are in inches [mm]









RECOMMENDED PCB LAYOUT

APX-VNG0031PSD-003/004

0.106 [2.70]

PIN OUT

LEAD

R2

COMMON

R3

R4 COMMON CATHODE

PIN

2

3

4



# **General Care and Handling Instructions**

#### Photodiodes:

#### Handling and Storage

- Handle Photodiodes gently to prevent damage.
- Avoid exposing Photodiodes to temperatures exceeding the storage temperature rating of the device.
- Maintain a non-condensing environment for optimum performance and lifetime.

#### Cleaning

 Gently clean the glass (borosilicate or quartz window) using a 50/50 mixture of Methanol and isopropyl alcohol and a soft, optical-grade pad.

# Special Considerations for Plastic or Epoxy Encapsulated Photodiodes

- Protect from intense light sources such as direct sunlight.
- Avoid exposure to harsh chemicals like THINNERS, ACETONE, and TRICHLOROETHYLENE.
- Cleaning with a 50/50 mixture of Methanol and isopropyl alcohol (IPA) is recommended. Cleaning in an ultrasonic bath is generally not recommended.

### **CdS Photocells:**

### Handling and Storage

- Handle CdS Photocells gently to prevent damage.
- Avoid exposing CdS Photocells to temperatures exceeding the storage temperature rating of the device.
- Maintain a non-condensing environment for optimum performance and lifetime.

# Cleaning

- Gently clean the glass or plastic covering using a 50/50
- mixture of Methanol and isopropyl alcohol and a soft, opticalgrade pad.

# Special Considerations

 DO NOT use Vapor Phase Soldering or Reflow Soldering for CdS components.

# Optocouplers and LEDs:

# Handling and Storage

- Handle Optocouplers and LEDs gently to prevent damage.
- Avoid exposing the devices to temperatures exceeding the storage temperature rating of the device.
- Maintain a non-condensing environment for optimum performance and lifetime.

# Cleaning

 For plastic molded devices, cleaning with a 50/50 mixture of Methanol and isopropyl alcohol is recommended. Cleaning in an ultrasonic bath is generally not recommended.

# **Special Considerations**

 Avoid exposing plastic molded devices or epoxy glob top devices to harsh chemicals like THINNERS, ACETONE, and TRICHLOROETHYLENE.

# **Legal Disclaimer**

Information in this data sheet is believed to be correct and reliable. However, no responsibility is assumed for possible inaccuracies or omission. Specifications are subject to change without notice.



# Electrostatic Discharge (ESD) Sensitivity:

All devices are considered ESD-sensitive. They are shipped in ESD protective packaging. When unpacking and using these products, anti-ESD precautions should be observed.

### Lead Trimming and Bending:

 Standard lead trimming after soldering is an acceptable practice; however, do not attempt to bend or modify the leads incorrectly, as it can damage the glass feed-through or the plastic encapsulant.

#### Soldering Instructions:

- Use a soldering iron with a tip temperature of 300°C max.
- Consult with your preferred solder manufacturer to determine a solder alloy and flux combination, as well as the reflow profile appropriate for your application.

#### **General Precautions for all Devices**

#### 1. Moisture Prevention:

Ensure devices are stored in a dry environment to prevent moisture ingress, which can cause damage during soldering. Refer to J-STD-20 for guidance on proper baking procedures to prevent moisture related damage.

## 2. Lead Splaying:

If required, carefully splay the leads of the devices according to the specific application needs. Be cautious when splaying leads, as improper techniques may damage the device. Consult technical support or device datasheets for guidance on lead splaying.

# 3. Mechanical Stress:

Handle devices with care throughout the installation process to prevent damage.

# 4. Circuit Protection and Layout:

Optimize the circuit design and layout to ensure proper functioning and prevent damage to the devices. Include appropriate protection measures like ESD protection diodes, current-limiting resistors, and voltage regulation.

# 5. After-Sale Support:

For troubleshooting and device-specific inquiries, please consult with our technical support team. They can offer valuable guidance and suggestions on handling, operation, and application-related questions. To reach them, please contact the Advanced Photonix Applications group at Techsupport@advancedphotonix.com.

